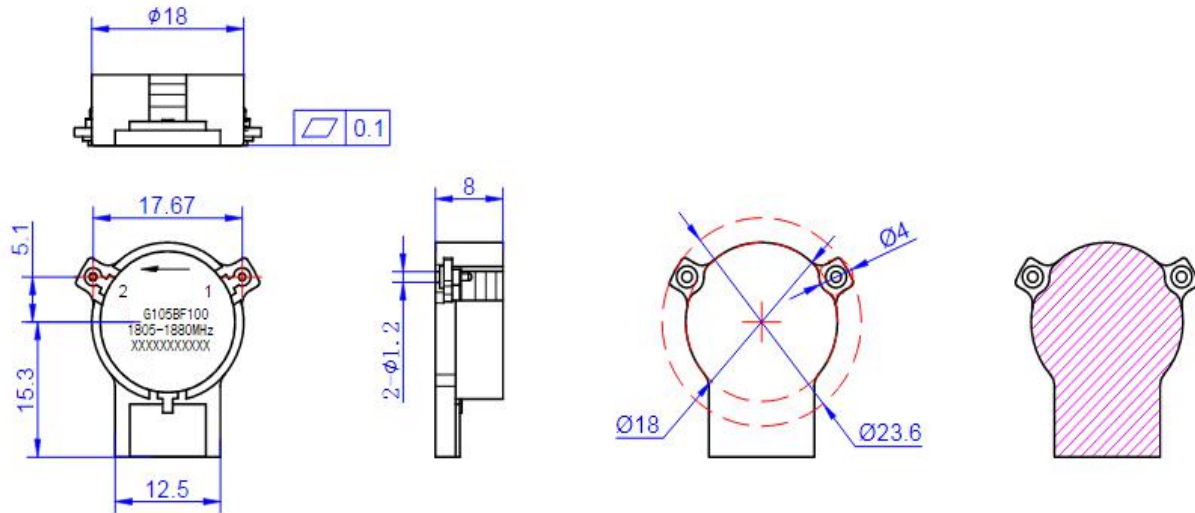


1.Features

UMTS, LTE Band
 PCB Soldering Re-flow
 Wide Operation Temperature Range -45 ~ 125°C
 Compact Package Design for PCB Applications

2.Dimensions



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G105BZ60-0.0(1480-1526)MH	1.480	1.526	1.5030	0.046	25	0.2	1.12	100	-74
G105BF60-0.0(1840-1900)MHz	1.840	1.900	1.8700	0.060	25	0.2	1.12	100	-74
G105BZ100-0.0(2200-2400)MHz	2.200	2.400	2.3000	0.200	25	0.25	1.12	100	-74
G105BZ60-0.0(2500-2700)MHz	2.500	2.700	2.6000	0.200	22	0.25	1.17	100	-74